



RE232-LF

- Epoxy fibre-glass FR4 1.60 mm
- Single-side 35 µm Cu
- Hot air leveling (HAL-leadfree)
- Component print
- Hole spacing 2.54 x 2.54 mm
- 40 x 60 tracks of bored holes
- 3-hole pads
- Hole diameter 1.02 mm (0.40")
- 4 rows DIP IC grid 7.62 mm, 15.24 mm with 48 terminal pins
- Max. working temperature 150 °C (320 °F)
- Size 114.30 mm x 165.10 mm (4.5" x 6.5")